

Immense Advance Tech.

## FEATURES

- Reference voltage 0.8V
- Input voltage as low as 1.4V and VPP voltage 5V
- 300mV dropout @2A
- Over current, short circuit and over temperature protection
- Enable function
- Low reverse leakage (output to input)
- High output voltage accuracy ±2%
- Power Good signal
- Adjustable output voltage by external resistors
- V<sub>OUT</sub> pull low resistance when disable

### **APPLICATION**

- Motherboards application
- Peripheral cards
- Network cards
- Set top boxes
- Notebook PC applications

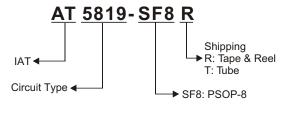
# DESCRIPTION

The AT5819 is a 2A low dropout high performance linear voltage regulator, that provides a low voltage, high current output with a minimum of external components, utilizing dual supply configuration.

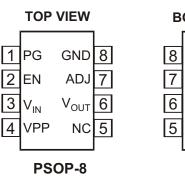
The AT5819 offers a low input voltage range from 1.4 V to 5.5V and is ideal for applications that need to convert down to 0.8V.

Additionally, the AT5819 is fully protected with current limit, short circuit and thermal shutdown. Also, there is an EN input which enables or shuts down the device.

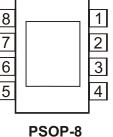
### ORDERING INFORMATION



### PIN CONFIGURATIONS









## PIN DESCRIPTIONS

Pin NO.	Pin Name	Pin Description	
Pin 1	PG	Assert high once $V_{\text{OUT}}$ reaches 92% of its rating voltage. Power Good Open Drain Output.	
Pin 2	EN	Chip Enable (Active-High).	
Pin 3	V <sub>IN</sub>	Supply Input Voltage.	
Pin 4	VPP	Supply Voltage of Control Circuitry.	
Pin 5	NC	No Internal Connection.	
Pin 6	V <sub>OUT</sub>	Output Voltage.	
Pin 7	ADJ	Set the output voltage by the internal feedback resistors when ADJ is grounded. If external feedback resistors is used: $V_{out} = \frac{0.8 (R1+R2)}{R2}$ (Figure 1.)	
Pin 8	GND	Ground.	

# **TYPICAL APPLICATION CIRCUITS**

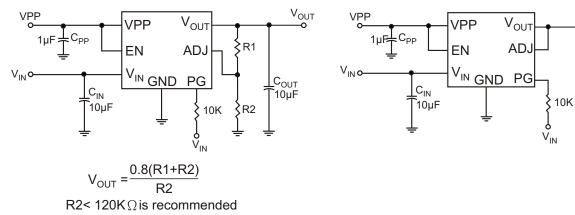


Figure 1. Adjustable Voltage Regulator

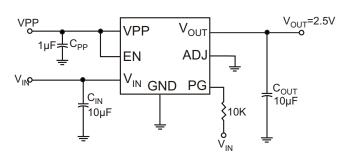


Figure 3. Fixed Voltage Regulator

Figure 2. Fixed Voltage Regulator

V<sub>OUT</sub>=0.8V

-0

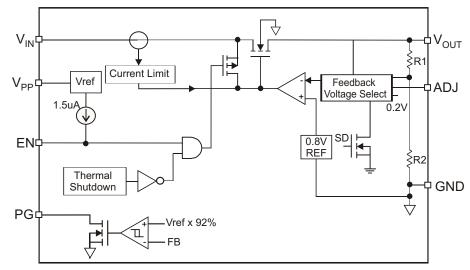
COUT

10µF



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### **BLOCK DIAGRAM**



### ABSOLUTE MAXIMUM RATINGS(Note 1)

Parameter	Symbol	Max Value	Unit
Supply Voltage, V <sub>IN</sub>	V <sub>IN</sub>	6	V
Control Voltage, VPP, EN	VPP	6	V
Output Voltage, V <sub>OUT</sub>	V <sub>OUT</sub>	6	V
Power Dissipation, P <sub>D</sub> @ T <sub>A</sub> =25°C PSOP-8(Exposed Pad)	P <sub>D</sub>	Internally Limited	W
Thermal Resistance Junction to Ambient (Note2) PSOP-8	$\Theta_{JA}$	36	°C/W
Junction Temperature	Т <sub>Ј</sub>	125	°C
Lead Temperature(Soldering) 5 Sec.	T <sub>LEAD</sub>	260	°C
Storage Temperature Range	T <sub>STG</sub>	-65 to +150	°C
ESD Susceptibility (Note 3) HBM (Human Body Mode)	V <sub>ESD</sub>	2	kV

## **RECOMMENDED OPERATING CONDITIONS** (Note 4)

Parameter	Symbol	Operation Conditions	Unit
Supply Voltage, V <sub>IN</sub>	V <sub>IN</sub>	1.4 to 5.5	V
Control Voltage, VPP	VPP	4.5 to 5.5	V
Output Voltage, V <sub>OUT</sub>	V <sub>OUT</sub>	0.8 to 5.5	V
Junction Temperature Range	TJ	-40 to 125	°C
Ambient Temperature Range	T <sub>A</sub>	-40 to 85	°C

Notes 1: Stresses listed as the above "Absolute Maximum Ratings" may cause permanent damage to the device. These are for stress ratings. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may remain possibility to affect device reliability.

Notes 2: 2 square inch of FR-4 , double sided, 1 oz. minimum copper weight.

Notes 3: Devices are ESD sensitive. Handling precaution recommended.

Notes 4: The device is not guaranteed to function outside its operating conditions.



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## **ELECTRICAL CHARACTERISTICS**

 $V_{IN} = V_{OUT} + 500 \text{mV}, V_{EN} = \text{VPP} = 5\text{V}, C_{IN} = C_{OUT} = 10 \text{uF}, T_A = T_J = 25^{\circ}\text{C}$ , unless otherwise specified.

Pa	arameter	Symbol	Conditions	Min	Тур	Max	Unit
V <sub>IN</sub>							
Supply Voltage, V <sub>IN</sub>		V <sub>IN</sub>		1.4		5.5	V
VPP		•					
VPP Opera	ation Voltage Range	VPP	VPP Input Range	4.5		5.5	V
VPP Shute	down Current	I <sub>PPL</sub>	V <sub>EN</sub> = 0V		10	20	μA
ADJ							
Adjustable	Pin Threshold	$V_{\rm TH\_ADJ}$		0.15	0.2	0.25	V
Reference (ADJ Pin \		V <sub>ADJ</sub>	V <sub>ADJ</sub> =V <sub>OUT</sub>	0.788	0.8	0.812	V
V <sub>OUT</sub>							
Fixed Out	put Voltage Range	V <sub>OUT</sub>	V <sub>IN</sub> =V <sub>OUT</sub> +500mV, V <sub>ADJ</sub> =GND	2.45	2.5	2.55	V
Line Regu	lation (V <sub>IN</sub> )	REG <sub>(LINE)</sub>	V <sub>IN</sub> =V <sub>OUT</sub> +0.5V to 5V, I <sub>OUT</sub> =1mA		0.2	1	%
Load Reg	ulation (Note7)	REG <sub>(LOAD)</sub>	$V_{IN} = V_{OUT} + 1V$ , $I_{OUT} = 10$ mA to 2A		0.2	1	%
Dropout V	oltage (Note 5)	V <sub>D</sub>	I <sub>OUT</sub> =2A		250	300	mV
Quiescent	Current (Note 6)	Ι <sub>Q</sub>			0.25	0.5	mA
Short Circu	it Protection Current				1.4		А
V <sub>OUT</sub> Pull Low Resistance			V <sub>EN</sub> =0V		90		Ω
Enable		•					
EN Input B	ias current	I <sub>EN</sub>	V <sub>EN</sub> = 0V		12	20	μA
EN	Logic-Low Voltage	V <sub>ENL</sub>	VPP= 5V			0.4	
Threshold	Logic-High Voltage	V <sub>ENH</sub>	VPP= 5V	1.6			V
Power Go	od					· I	
PG Rising Threshold					92		%
PG Hysteresis					7		%
Thermal P	rotection						
Thermal Sh	utdown Temperature	T <sub>SD</sub>			150		°C
Thermal Sh	nutdown Hysteresis				30		°C

Notes 5: Defined as the input to output differential at which the output voltage drops to 2% below the value measured at a differential of 0.8V and V<sub>OUT</sub> set to 2.5V.

**Notes 6:** Quiescent, or ground current, is the difference between input and output currents. It is defined by  $I_Q = I_{IN} - I_{OUT}$  under no load condition ( $I_{OUT} = 0$ mA). The total current drawn from the supply is the sum of the load current plus the ground pin current.

Notes 7: Regulation is measured at constant junction temperature by using a pulsed current .



### **APPLICATION INFORMATION**

#### Adjustable Mode Operation

The output voltage of AT5819 is adjustable from 0.8V to 5.5V by external voltage divider resisters as shown in Typical Application Circuit(Figure 1). The value of resisters R1 and R2 should be more than  $10K\Omega$  to reduce the power loss.

#### Enable

The AT5819 goes into shutdown mode when the EN pin is in the logic low condition. During this condition, the pass transistor, error amplifier, and band gap are turned off, reducing the supply current to  $10\mu$ A typical. The AT5819 goes into operation mode when the EN pin is in the logic high condition. If the EN pin is floating, NOTE that the AT5819 internal initial logic level. For AT5819, the EN pin function pulls high level internally. So the regulator will be turn on when EN pin is floating.

#### **Output Capacitor**

A minimum bulk capacitance of  $10\mu$ F ceramic, along with a  $0.1\mu$ F ceramic decoupling capacitor is recommended. Increasing the bulk capacitance will improve the overall transient response. The use of multiple lower value ceramic capacitors in parallel to achieve the desired bulk capacitance will not cause stability issues. Although designed for use with ceramic output capacitors.

#### **External Voltage Selection Resistors :**

The use of 1% resistors, and consider for system stability and power losing , we recommend to design high dividing resistance (R2<120K $\Omega$ ) to strengthen the benefits which AT819 has inherent.

#### **Input Capacitor**

A minimum of  $10\mu$ F ceramic capacitor is recommended to be placed directly next to the V<sub>IN</sub> pin. This allows for the device being some distance from any bulk capacitance on the rail. Additionally, bulk capacitance may be added closely to the input supply pin of the AT5819 to ensure that V<sub>IN</sub> does not sag, improving load transient response.

#### **Power Good**

The Power Good function is an open-drain output. Connects  $10K\Omega$  Pull up resistor to V<sub>OUT</sub> to obtain an output voltage. The PG pin will output high immediately after the output voltage arrives 92% of normal output voltage.

#### **Power Dissipation**

For continuous operation, do not exceed absolute maximum operation junction temperature 125°C. The power dissipation definition in device is:

$$\mathsf{P}_{\mathsf{D}} = (\mathsf{V}_{\mathsf{IN}} - \mathsf{V}_{\mathsf{OUT}}) \mathsf{x} \mathsf{I}_{\mathsf{OUT}} + \mathsf{V}_{\mathsf{IN}} \mathsf{x} \mathsf{I}_{\mathsf{Q}}$$

The maximum power dissipation depends on the thermal resistance of IC package, PCB layout, the rate of surroundings airflow and temperature difference between junctions to ambient. The maximum power dissipation can be calculated by following formula:

$$\mathsf{P}_{\mathsf{D}(\mathsf{MAX})} = (\mathsf{T}_{\mathsf{J}(\mathsf{MAX})} - \mathsf{T}_{\mathsf{A}(\mathsf{MAX})}) / \Theta_{\mathsf{JA}}$$

Where  $T_{J(MAX)}$  is the maximum operation junction temperature 125°C,  $T_A$  is the ambient temperature and the  $\Theta_{JA}$  is the junction to ambient thermal resistance.

For recommended operation conditions specification of AT5819, where  $T_{J(MAX)}$  is the maximum junction temperature of the die (125°C) and  $T_A$  is the maximum ambient temperature. The junction to ambient thermal resistance for PSOP-8 (Exposed Pad) package is 36°C /W on the standard JEDEC 51-7 (4 layers, 2S2P) thermal test board. The copper thickness is 2oz. The maximum power dissipation at  $T_{A(MAX)}$ =85°C can be calculated by following formula:

P<sub>D(MAX)</sub>=(125°C-85°C)/(36°C/W)=1.11W

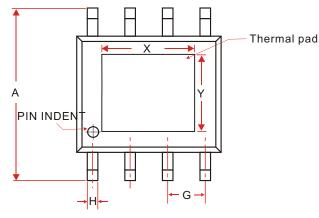
(PSOP-8 Exposed Pad on the minimum layout)

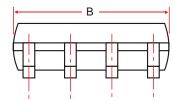
2.0A Low Dropout Regulator with Enable



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## **PSOP-8 PACKAGE OUTLINE DIMENSIONS**

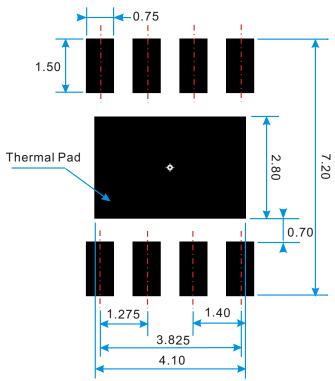




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	DIMENSIONS			
REF.	Millimeters			
	Min.	Max.		
A	5.80	6.20		
В	4.80	5.00		
С	3.80	4.00		
D	0°	8°		
E	0.40	0.90		
F	0.15	0.26		
М	0	0.25		
Н	0.31	0.51		
L	1.35	1.75		
G	1.27 TYP.			
Х	3.30 TYP.			
Y	2.50 TYP.			

## **PSOP-8 PACKAGE FOOTPRINT (mm)**



#### Note:

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